LINXENS
CONNECTING YOU TO SUCCESS

SMART-ePASSPORT Product Family

Product Range

Providing high-security RFID inlays and e-covers of outstanding quality to customers worldwide helps improve secure identification and increase the effectiveness of border control processes.

LINXENS's SMART-ePassport (ePP) product family guarantees reliable and flexible products that meet customers' stringent demands and exceed industry standards.

In terms of secure travel documents, LINXENS offers a wide range of tailor-made ePassport Inlay and eCover products.

Our ePassport products are typically manufactured applying a number of the company's proprietary and patent protected technologies consisting of a wire-embedded antenna on a carrier substrate connected to a chip module.

The laminated inlay is then smoothly incorporated either into the data page or the back cover of the passport.

One of the most globally recognized LINXENS patents in this respect is DURASOFT®, a resilient material that enhances a document's reliability and durability significantly. LINXENS's DURASOFT® has pioneered globally and been the material of choice in the ePassport industry for more than a decade.

Overview

Operating Frequency
13.56 MHz
Operating Temperature
-25°C to + 50°C

International Standards

- ISO 14443
- ICAO Compliance
- EAL 6

Application Area

- ePassport

Features

- HINGE REINFORCEMENT
- SMART-AC (Anti-Crack)
- SMART-CAP

LINXENS
CONNECTING YOU TO SUCCESS

SMART-ePASSPORT Product Family

Product Range

Product Name	Thickness	Sheet Format	Features*	Available ICs
Durasoft® 3.0 ePP-Inlay	ca. 400µm	2up, 3up	HINGE-REINFORCEMENT SMART-AC SMART-CAP	Infineon, NXP, STMicroelectronics, Samsung
Paper Inlay 1.0 ePP-Inlay	ca. 400µm	2up, 3up	HINGE-REINFORCEMENT SMART-AC SMART-CAP	Infineon, NXP, STMicroelectronics, Samsung
eCover Textile Cover	ca. 700µm	2up, 3up	HINGE-REINFORCEMENT SMART-AC SMART-CAP	Infineon, NXP, STMicroelectronics, Samsung
eCover Paper Cover	ca. 700µm	2up, 3up	HINGE-REINFORCEMENT SMART-AC SMART-CAP	Infineon, NXP, STMicroelectronics, Samsung
SMART-SL ePP PRELAM®	ca. 300µm	customer specific	SMART-AC	Infineon, NXP, STMicroelectronics, Samsung

Additional memory, protocol and product configurations are available upon request.

Features*

- HINGE-REINFORCEMENT describes a special woven material that is used in order to increase the tear resistance of ePP inlays in the hinge area.
- SMART-AC is an anti-crack features, that prevents micro-cracks around the chip module inside the card body. It combines mechanical robustness within PC-based contactless inlays.
- SMART-CAP means Chip Activation Protection and takes privacy concerns of travelers serious and ensures that personal information stored on the advanced encrypted microcontroller chip of an electronic passport can only be read by authorized parties.

Linxens Group
For further information: contact@linxens.com - http://linxens.com/en/contact-us

© LINXENS 2017
All rights reserved. Reproduction in whole or in part is prohibited without the prior written consent of the copyright owner. The information presented in this document does not form part of any quotation or contract, is believed to be accurate and reliable and may be changed without notice. No liability will be accepted by the publisher for any consequence of its use.